

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jeng Chang Her</td> <td>05/27/2013</td> </tr> <tr> <td>Hung Jui Chang</td> <td>05/27/2013</td> </tr> <tr> <td>Li Te Hsu</td> <td>05/27/2013</td> </tr> <tr> <td>Chung-Bin Tseng</td> <td>05/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	Jeng Chang Her	05/27/2013	Hung Jui Chang	05/27/2013	Li Te Hsu	05/27/2013	Chung-Bin Tseng	05/27/2013		
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CORRESPONDENCE DATA													
Fax Number: 2142000853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 972-739-8635 Email: Kim.Reyes@haynesboone.com Correspondent Name: Haynes and Boone, LLP Address Line 1: IP Section, 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219													
ATTORNEY DOCKET NUMBER:	2012-0927 / 24061.2541												
NAME OF SUBMITTER:	David M. O'Dell												

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Signature:	/David M. O'Dell/
Date:	06/28/2013
Total Attachments: 3 source=24061_2541_Assignment#page1.tif source=24061_2541_Assignment#page2.tif source=24061_2541_Assignment#page3.tif	

Docket No.: 2012-0927 / 24061.2541
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Jeng Chang Her of No. 22-10, Yuxin Rd., East District
Tainan City 701, Taiwan, R.O.C.
- (2) Hung Jui Chang of No. 235, Sec. 2, Yuanji Rd., Shetou Shiang
Changhua County 511, Taiwan, R.O.C.
- (3) Li Te Hsu of No. 51, Lane 35, Guangwun Rd., Shanhua Township
Tainan County 741, Taiwan R.O.C.
- (4) Chung-Bin Tseng of No. 638, Datong St., Yongkang Dist.
Tainan City 710, Taiwan, R.O.C.

have invented certain improvements in

OXIDE FILM FORMATION OF A BSI IMAGE SENSOR DEVICE

for which we have filed and executed an application for Letters Patent of the United States of America on
June 28, 2013 Serial No. 13/931,500; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal

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proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jeng Chang Her

Residence Address: No. 22-10, Yuxin Rd., East District
Tainan City 701, Taiwan, R.O.C.

Dated: 2013, 5, 27

Jeng Chang Her.
Inventor Signature

Inventor Name: Hung Jui Chang

Residence Address: No. 235, Sec. 2, Yuanji Rd., Shetou Shiang
Changhua County 511, Taiwan, R.O.C.

Dated: 2013. 5. 27

Hung Jui Chang.
Inventor Signature

Inventor Name: Li Te Hsu

Residence Address: No. 51, Lane 35, Guangwun Rd., Shanhua Township
Tainan County 741, Taiwan R.O.C.

Dated: 2013. 5. 27

Li - Te Hsu.
Inventor Signature

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Inventor Name: Chung-Bin Tseng

Residence Address: No. 638, Datong St., Yongkang Dist.
Tainan City 710, Taiwan, R.O.C.

Dated: 20130527

Chung-Bin Tseng
Inventor Signature